TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ( $L^2-\pi$ -MOS V)

# 2 S K 2 7 8 2

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS** 

#### 4V Gate Drive

Low Drain-Source ON Resistance :  $R_{DS(ON)} = 0.039\Omega$  (Typ.)

High Forward Transfer Admittance :  $|Y_{fs}| = 11S \text{ (Typ.)}$ 

Low Leakage Current :  $I_{DSS} = 100 \mu A \text{ (Max.)} \text{ (V}_{DS} = 60 \text{ V)}$ 

Enhancement-Mode :  $V_{th} = 0.8 \sim 2.0 \text{V } (V_{DS} = 10 \text{V}, I_D = 1 \text{mA})$ 

#### MAXIMUM RATINGS (Ta = 25°C)

100 D 100 TO								
CHARACTERIS	SYMBOL	RATING	UNIT					
Drain-Source Voltage	$v_{ m DSS}$	60	V					
Drain-Gate Voltage (RG	$v_{ m DGR}$	60	V					
Gate-Source Voltage	$v_{GSS}$	±20	V					
Drain Current	DC	$I_{\mathrm{D}}$	20	A				
	Pulse	$I_{\mathrm{DP}}$	50	A				
Drain Power Dissipation	$P_{\mathrm{D}}$	40	W					
Single Pulse Avalanche	EAS	156	mJ					
Avalanche Current	$I_{AR}$	20	A					
Repetitive Avalanche En	$\mathrm{E}_{\mathrm{AR}}$	4	mJ					
Channel Temperature	$\mathrm{T_{ch}}$	150	°C					
Storage Temperature Ra	$\mathrm{T_{stg}}$	-55~150	°C					

#### THERMAL CHARACTERISTICS

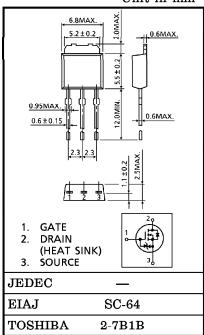
CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R <sub>th (ch-c)</sub>	3.125	°C/W
Thermal Resistance, Channel to Ambient	R <sub>th (ch-a)</sub>	125	°C/W

#### Note;

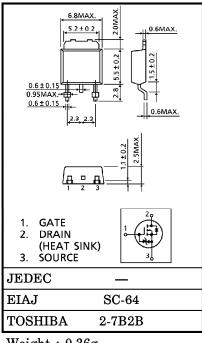
- Repetitive rating; Pulse Width Limited by Max. junction temperature.
- \*\*  $V_{DD} = 25V$ ,  $T_{ch} = 25^{\circ}C$ ,  $L = 530 \mu H$ ,  $R_{G} = 25\Omega$ ,  $I_{D} = 20A$

This transistor is an electrostatic sensitive device. Please handle with caution.

### INDUSTRIAL APPLICATIONS Unit in mm



Weight: 0.36g



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# ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARAC	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	Current	$I_{GSS}$	$V_{GS} = \pm 16V$ , $V_{DS} = 0V$	_	_	±10	μA
Drain Cut-off	Current	$I_{ m DSS}$	$V_{DS}=60V, V_{GS}=0V$	_	_	100	$\mu$ A
Drain-Source Voltage	Breakdown		I <sub>D</sub> =10mA, V <sub>GS</sub> =0V	60	_	_	V
Gate Thresho	ld Voltage	$v_{th}$	$V_{DS} = 10V$ , $I_D = 1mA$	0.8	_	2.0	V
Drain-Source	ON Resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> =4V, I <sub>D</sub> =5A V <sub>GS</sub> =10V, I <sub>D</sub> =10A	_	0.06	0.09	Ω
Forward Tran Admittance	nsfer	Y <sub>fs</sub>	$V_{ m DS} = 10 V, I_{ m D} = 10 A$	7	11	_	S
Input Capacit	ance	$C_{iss}$		_	880	_	
Reverse Transfer Capacitance		$\mathrm{C}_{\mathbf{rss}}$	$V_{\mathrm{DS}}$ =10V, $V_{\mathrm{GS}}$ =0V f=1MHz	_	90	_	pF
Output Capacitance		$C_{oss}$		_	330	_	
Switching Time Fall Time	Rise Time	t <sub>r</sub>	V <sub>GS</sub> <sup>10V</sup> I <sub>D</sub> =10A R <sub>L</sub> =3.0Ω	_	15	_	ns
	Turn-on Time	t <sub>on</sub>		_	25	_	
	$t_f$	m = m = 0	-	30	_	115	
	Turn-off Time	t <sub>off</sub>	$V_{\mathrm{IN}}: t_{\mathrm{r}}, t_{\mathrm{f}} < 5 \mathrm{ns}, \ V_{\mathrm{DD}} = 30 \mathrm{V}$ $\mathrm{Duty} \leq 1\%, t_{\mathrm{W}} = 10 \mu \mathrm{s}$	_	100	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		$Q_{\mathrm{g}}$	V <sub>DD</sub> ≒48V, V <sub>GS</sub> =10V	_	25	_	nC
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{D}=20A$		19	_	] "
Gate-Drain ("Miller") Charge		$ m Q_{gd}$		_	6	<u> </u>	

# SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	20	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	50	A
Diode Forward Voltage	$V_{ m DSF}$	$I_{DR}$ =20A, $V_{GS}$ =0V	_	_	-2.0	V
Reverse Recovery Time	$\mathfrak{t}_{\mathtt{rr}}$	$I_{DR}$ =20A, $V_{GS}$ =0V		60	_	ns
Reverse Recovery Charge	$\mathrm{Q_{rr}}$	$dI_{ m DR}$ / $dt$ = 50A / $\mu$ s		45		μC

## **MARKING**

